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JULY 2005

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

Applicant(s): Palmteer

Application No: 09/966,222

Filing Date: September 28, 2001

Attorney Docket No: 17658

Title: IMPROVED LEADFRAME-BASED
CHIP SCALE PACKAGE

Art Group: 2891

Examiner: Zarneke, David A.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on September 1, 2005.

Danielle M. Langdon

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION DATED JUNE 1, 2005

Dear Sir:

This reply is being filed timely in response to the Office Action dated June 1, 2005, in connection with the above-identified patent application. The Commissioner is hereby authorized to charge any fees which may be required, any deficiencies that may arise, and to credit any overpayment which may be owed to Applicant in connection with this action and application in general to Deposit Account No. 19-5425.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.